



TIF[®]050AB-11S is a high thermal conductivity liquid gap-filling material adopting a two-component formulation, which can be tailored to differentiated curing requirements under varying temperatures. Specifically engineered for low-stress assembly scenarios and high compressive modulus application requirements, this material forms intimate contact with mating surfaces during electronic product assembly, effectively reducing contact thermal resistance while delivering excellent electrical insulation performance. After curing, its performance is equivalent to that of thermal conductive silicone sheets, with outstanding high-temperature resistance and anti-aging stability.

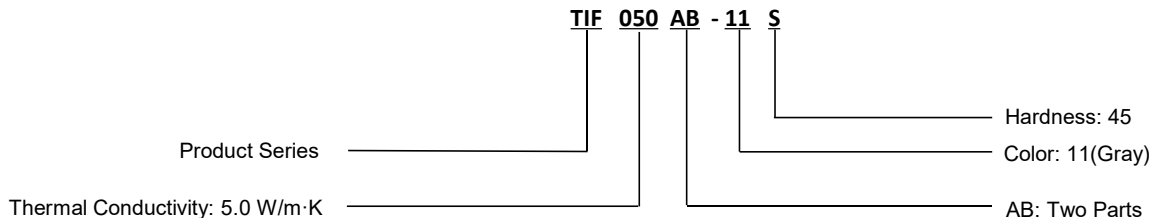
Features

- › High thermal conductivity
- › Two-part formulation for easy storage
- › Excellent low and high temperature mechanical and chemical stability
- › Ultra-conforming low-stress interface application
- › Ambient or accelerated cure schedules
- › Optimized shear thinning characteristics for ease of dispensing

Applications

- › Computer and peripherals
- › Telecommunications
- › Automotive electronics
- › Thermally conductive vibration dampening
- › Heat sink and any heat generating semiconductor

Product Identifier



Product Specification

50 cc/pcs, 400 cc/pcs, or customized packaging for automation applications.

For information on products of different specifications, please contact our company.

If you want to learn more about our thermal conductivity products, please visit our official website.

Global solutions: Local support

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Typical Properties of TIF [®] 050AB-11S		
Uncured Material Properties		
Property	Value	Test Method
Construction & Composition	Ceramic filled silicon material	-
Color/Part A	White	Visual
Color/Part B	Gray	Visual
Component A Viscosity (mPa·s)	2,800,000	GB/T 10247
Component B Viscosity (mPa·s)	3,000,000	GB/T 10247
Flow Rate (g/min)	6	Ziitek Test Method (50 cc syringe/1.5 mm orifice/90 psi)
Density (g/cm ³)	3.2	ASTM D792
Bond Line Thickness (mm)	0.1	-
Thermal Resistance (°C·in ² /W)@10psi	0.08	ASTM D5470
Thermal Resistance (°C·in ² /W)@50psi	0.07	ASTM D5470
Mix Ratio	1:1	-
Shelf Life	12 months	-
Cure Schedule		
Pot Life @ 25°C	30 min	Ziitek Test Method
Cure @ 25°C	60 min	Ziitek Test Method
Cure @ 70°C	30 min	Ziitek Test Method
Cure Material Properties		
Color	Gray	Visual
Hardness (Shore OO)	45	ASTM D2240
Recommended Operating Temperature (°C)	-45 ~ 200	-
Breakdown Voltage (V/mm)	≥5500	ASTM D149
Flame Rating	V-0	UL 94
Thermal Conductivity (W/m·K)	5.0	ASTM D5470